

www.Jameco.com + 1-800-831-4242

The content and copyrights of the attached material are the property of its owner.

Jameco P/N 42198

5101 FAMILY 256 x 4 BIT STATIC CMOS RAM

P/N	Typ. Current @ 2V (µA)	Typ. Current @ 5V (μΑ)	Max Access (ns)
5101L	0.14	0.2	650
5101L-1	0.14	0.2	450
5101L-3	0.70	1.0	650

Single +5V Power Supply

 Ideal for Battery Operation (5101L)

Directly TTL Compatible: All Inputs and Outputs

Three-State Output

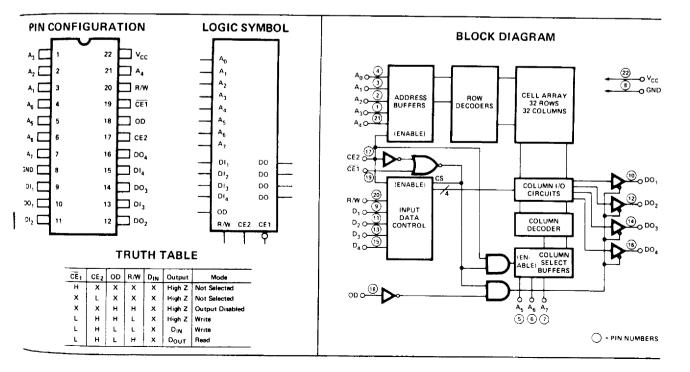
The Intel[®] 5101 is an ultra-low power 1024-bit (256 words \times 4 bits) static RAM fabricated with an advanced ion-implanted silicon gate CMOS technology. The device has two chip enable inputs. Minimum standby current is drawn by this device when CE2 is at a low level. When deselected the 5101 draws from the single 5-volt supply only 10 microamps. This device is ideally suited for low power applications where battery operation or battery backup for non-volatility are required.

The 5101 uses fully DC stable (static) circuitry; it is not necessary to pulse chip select for each address transition. The data is read out non-destructively and has the same polarity as the input data. All inputs and outputs are directly TTL compatible. The 5101 has separate data input and data output terminals. An output disable function is provided so that the data inputs and outputs may be wire OR-ed for use in common data I/O systems.

The 5101L has the additional feature of guaranteed data retention at a power supply voltage as low as 2.0 volts.

A pin compatible N-channel static RAM, the Intel[®] 2101A, is also available for low cost applications where a 256 \times 4 organization is needed.

The Intel ion-implanted, silicon gate, Complementary MOS (CMOS) process allows the design and production of ultra-low power, high performance memories.



Absolute Maximum Ratings *

Ambient Temperature Under Bias –10°C to 80°C
Storage Temperature
Voltage On Any Pin
With Respect to Ground , -0.3V to V _{CC} +0.3V
Maximum Power Supply Voltage +7.0V
Power Dissipation 1 Watt

D. C. and Operating Characteristics

 $T_A = 0^{\circ}C$ to $70^{\circ}C$, $V_{CC} = 5V \pm 5\%$ unless otherwise specified.

*COMMENT:

Stresses above those listed under "Absolute Maximum Rating" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or at any other condition above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Symbol	Parameter		L and 51 Limits Typ.[1]			5101L-3 Limits Typ.[1]		Units	Test Conditions
IL2[2]	Input Current		5			5		nA	
_{LO} [2]	Output Leakage Current			1			1	μA	CE1=2.2V, V _{OUT} = 0 to V _{CC}
I _{CC1}	Operating Current		9	22		9	22	mA	V _{IN} ≃V _{CC} , Except CE1 ≤ 0.65V, Outputs Open
I _{CC2}	Operating Current		13	27		13	27	mΑ	V _{IN} =2.2V, Except CE1 ≤ 0.65V, Outputs Open
ICCL[2]	Standby Current			10			200	μΑ	CE2 ≤ 0.2V, T _A = 70° C
VIL	Input Low Voltage	-0.3		0.65	-0.3		0.65	ν	
VIH	Input High Voltage	2.2		Vcc	2.2		Vcc	V	
VOL	Output Low Voltage			0.4			0.4	V	I _{OL} =2.0 mA
Voн	Output High Voltage	2.4			2.4			V	1 _{0H} = -1.0 mA

Low V_{CC} Data Retention Characteristics (For 5101L, 5101L-1 and 5101L-3) $T_A = 0^{\circ} C$ to 70° C

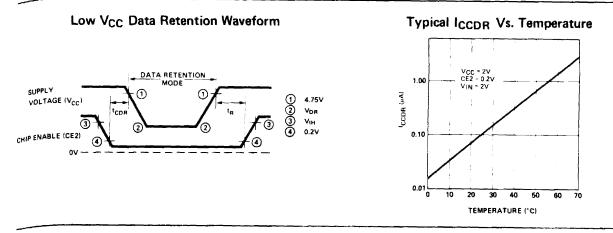
Symbol	Parameter	Min.	Typ.[1]	Max.	Units	Test Cor	nditions
V _{DR}	V _{CC} for Data Retention	2.0			V		
CCDR1	5101L or 5101L-1 Data Retention Current		0.14	10	μA	CE2 ≤ 0.2V	V _{DR} =2.0V, T _A =70° C
ICCDR2	5101 L-3 Data Retention Current		0.70	200	μA		V _{DR} = 2.0V, T _A = 70° C
t _{CDR}	Chip Deselect to Data Retention Time	0			ns		
t _R	Operation Recovery Time	t _{RC} [3]			ns		

NOTES:

1. Typical values are $T_A \approx 25^{\circ}$ C and nominal supply voltage.

2. Current through all inputs and outputs included in ICCL measurement.

3. tRC = Read Cycle Time.



A.C. Characteristics $T_A = 0^{\circ}C$ to $70^{\circ}C$, $V_{CC} = 5V \pm 5\%$, unless otherwise specified.

		1	1L-1 ts (ns)	5101L and 5101L-3 Limits (ns)	
Symbol	Parameter	Min.	Max.	Min.	Max
trc .	Read Cycle	450		650	
tA	Access Time		450		650
tco1	Chip Enable ($\overline{CE 1}$) to Output		400		600
tc02	Chip Enable (CE 2) to Output		500		700
top	Output Disable to Output		250		350
tDF	Data Output to High Z State	0	130	0	150
toh1	Previous Read Data Valid with Respect to Address Change	0		0	
toh2	Previous Read Data Valid with Respect to Chip Enable	0		0	
TE CYCLI					
twc	Write Cycle	450		650	
t _{AW}	Write Delay	130		150	
tcw1	Chip Enable (CE 1) to Write	350		550	·
tcw2	Chip Enable (CE 2) to Write	350		550	· · · · · · · · · · · · · · · · · · ·
tow	Data Setup	250		400	
t _{DH}	Data Hold	50		100	
twp	Write Pulse	250		400	
twr	Write Recovery	50		50	
t _{DS}	Output Disable Setup	130		150	

A.C. CONDITIONS OF TEST

input Pulse Levels:	+0.65 Volt to	2.2 Volt
input Pulse Rise and	Fall Times:	20 nsec
Timing Measurement	Reference Level:	1.5 Volt
Output Load:	1 TTL Gate and C_L	- 100pF

Capacitance^[2]T_A = 25°C, f = 1 MHz

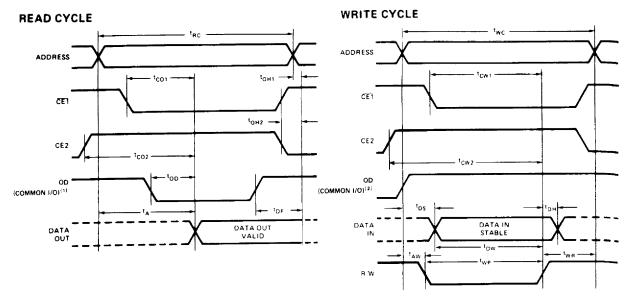
Symbol	Test	Limits (pF)		
зушьог	Test	Тур.	Max.	
C _{IN}	Input Capacitance (All Input Pins) V _{IN} = 0V	4	8	
COUT	Output Capacitance V _{OUT} = 0V	8	12	

NOTES: 1. Typical values are for $T_A = 25^{\circ}C$ and nominal supply voltage.

2. This parameter is periodically sampled and is not 100% tested.

Waveforms

. ...



NOTES:

- 1. OD may be tied low for separate I/O operation.
- During the write cycle, OD is "high" for common I/O and "don't care" for separate I/O operation.